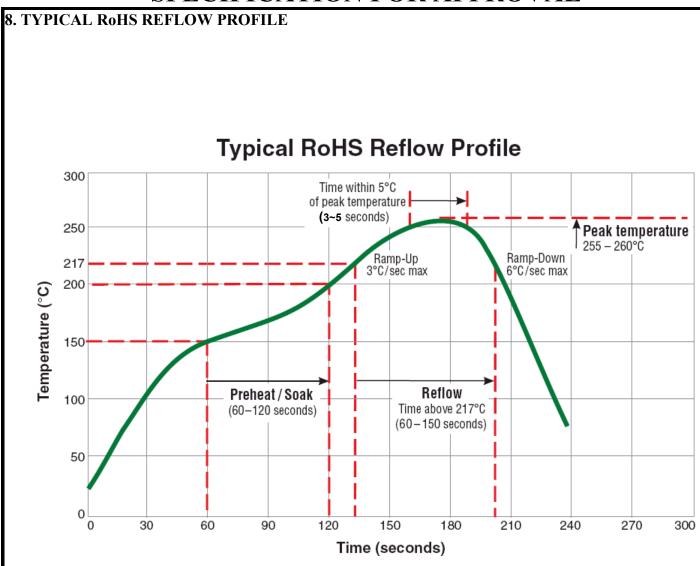


ELECTRICAL SPEC				ODE		
Part number	Inductance (µH) ±20%	Test Frequency (MHz)	Q MIN.	SRF (MHz) MIN.	DC Resistance (Ω) MAX.	Rated Current (mA)
FL201209I-100M-LRH	10	2	50	24	0.50	125
NOTE: 1. Test level: 100 mV						
ELECTRICAL CURV	VЕ					
		INDUCTANCE	vs. FREQU	ENCY		
	15					
	9 6					
	3					
	0 L 1	10 Frequenc	100 v (MHz)	100	00 3000	
	() vs. FREQUENCY	CHARAC	TERISTICS	5	
	100					
	80					
	60					
	° 40					
	20					
	1	10 Frequenc	100 _{y (MHz)}	100	00 3000	

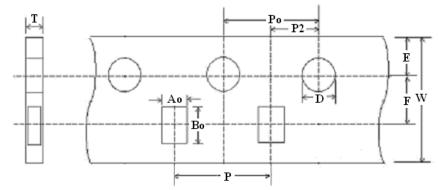
7. RELIABILITY PERFORMANCE

Test Item	Test Condition	Criteria		
Temperature Cycle	a. Temperature: -40 ~ +85°C b. Cycle: 100 cycles c. Dwell time: 30minutes Measurement: at ambient temperature 24 hrs after test completion	a. No mechanical damage b. Induction value should be within ±10% of the initial value c. Q vale should be within ±30% of the initial value		
Operational Life	a. Temperature: 125℃±5℃ b. Test time: 1000 hrs c. Apply current: full rated current Measurement: at ambient temperature 24 hrs after test completion	a. No mechanical damage b. Induction value should be within ± 10 % of the initial value c. Q vale should be within ±30% of the initial value		
Biased Humidity	 a. Temperature: 40°C±2°C b. Humidity: 90 ~ 95% RH c. Test time: 1000 hrs d. Apply current: full rated current Measurement: at ambient temperature 24 hrs after test completion 	a. No mechanical damage b. Induction value should be within ±10% of the initial value c. Q vale should be within ±30% of the initial value		
Resistance to Solder Heat	a. Solder temperature: 260±5℃ b. Flux: Rosin c. DIP time: 10±1 sec	 a. More than 95% of terminal electrode should be covered with new solder b. No mechanical damage c. Induction value should be within ±10% of the initial value d. Q vale should be within ±30% of the initial value 		
Adhesive Test	a. Reflow temperature: 245°C It shall be Soldered on the substrate applying direction parallel to the substrate b. Apply force(F): 5 N Test time: 10 sec	a. No mechanical damage b. Soldering the products on PCH after the pulling test force > 5 N		
Steam Aging Test	a. Temperature: 93℃ b. Test time: 8 hrs c. Solder temperature: 235±5℃ d. Flux: Rosin e. DIP time: 5±1 sec	More than 95% of terminal electrode should be covered with new solder		



9. PACKING

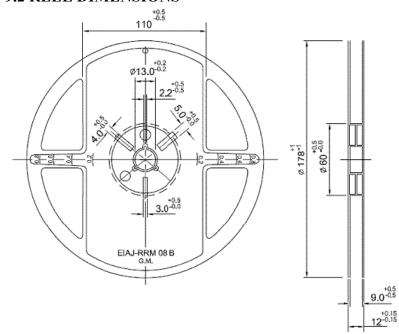
9.1 PAPER CARRIER



UNIT : mm

W	Р	Е	F	D	Ро	P2	Ao	Bo	Т
8.00±0.10	4.00±0.10	1.75±0.10	3.50±0.10	1.56±0.10	4.00±0.10	2.00±0.10	1.50±0.05	2.30±0.05	0.95±0.05

9.2 REEL DIMENSIONS



9.3 Packaging Quantity

Reel	Inner Box			
4,000 Pcs	5 Reels			